

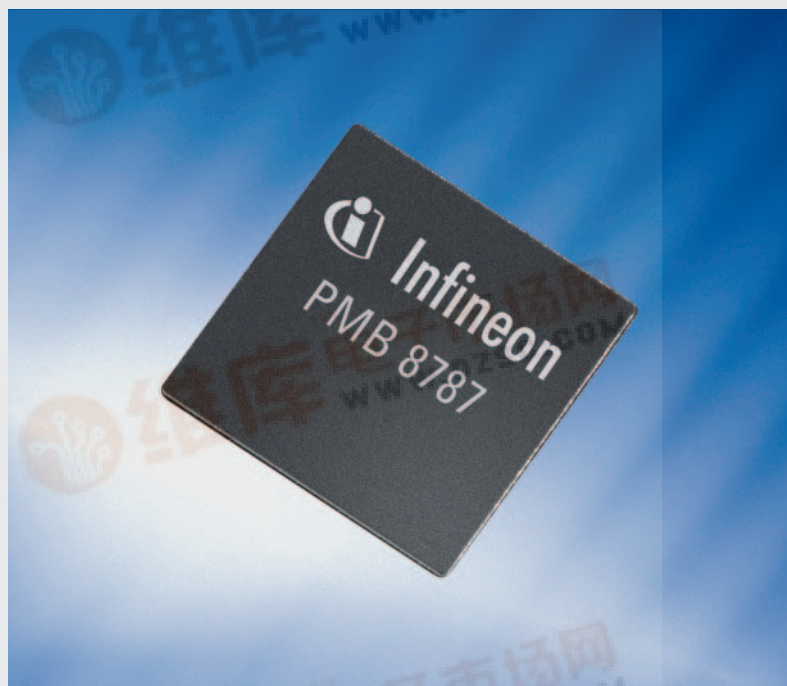
Dual-Band Modem IC (PHY) for WLAN System Solutions

The PMB 8787 provides the complete modem functionality for a dual-band wireless LAN chipset.

It contains the signal processing functionality for both the DSSS/CCK and the OFDM modulation/demodulation needed for an 802.11a/b/g compliant system.

The PMB 8787 is designed to form an Infineon WLAN chipset in combination with the PMB 8680 dual-band RF Transceiver, the PMB 8825 dual-band Power Amplifier and the PMB 8789 MAC IC.

The device is fabricated in an advanced 0.13 μm CMOS-technology and will be available in a LFBGA-81 package.



Features

- Advanced low power CMOS technology
- Supply voltage 3.3 V for MAC/RF interface and 1.5 V for core and analog supply
- Full support of 802.11a (54 Mbit @ 5 GHz) OFDM
- Full support of 802.11g (54 Mbit @ 2.4 GHz) OFDM
- Market proven 802.11b CCK/DSSS signal processing
- Data flow/low power architecture
- Radar/CW Detection (802.11h)
- Adaptive data rate selection due to SNR measurement
- Channel selection due to silence measurement
- Proven high performance mixed signal blocks (ADC/DAC, PLL)
- Low power A/D Converter

Applications

- High data-rate wireless LAN
- PC card wireless LAN adapters
- (Mini) PCI wireless LAN cards
- CardBus wireless LAN adapters
- Compact flash wireless LAN cards
- USB wireless LAN adapters
- Wireless LAN modules, access points, bridge products, and point-to-multipoint systems

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The diagram illustrates the MMIOFDM module architecture, showing the flow of data and control signals between various components. The main components are:

- MDI-MUX**: Multi-Drop Input Multiplexer, connected to the MDI and the TX-FSM.
- MDI-RX/TX Data Bridge**: Bridges the MDI and the OFDM PHY.
- OFDM - Module**: Contains the OFDM PHY, OFDM FSM, Radar-Detect, Int./Dec., and AGC.
- TX-FSM**: Transmitter Finite State Machine, connected to the MDI-MUX, MDI-RX/TX Data Bridge, and RX-FSM.
- RX-FSM**: Receiver Finite State Machine, connected to the TX-FSM, CCK/CW Detect, and CCK PHY.
- CCK/CW Detect**: Clocked Carrier/Karlovitz/Chirp Waveform Detector, connected to the RX-FSM and CCK PHY.
- CCK PHY**: Clocked Carrier/Karlovitz/Chirp Waveform Physical Layer, connected to the CCK/CW Detect and Resampling.
- Resampling 22/20 MHz**: Resampling block, connected to the CCK PHY and RF-Control.
- Power-Estimation**: Power Estimation block, connected to the RF-Control and AGC.
- RF-Control**: Radio Frequency Control block, connected to the AGC, RF 3-Wire, Ant.-Sw. RXEN TXEN PAON, PA-DAC PA-ADC, and the OFDM - Module.
- RF 3-Wire**: Radio Frequency 3-Wire interface.
- Ant.-Sw. RXEN TXEN PAON**: Antenna Switch, Receiver Enable, Transmitter Enable, and Power Amplifier On/Off control.
- PA-DAC PA-ADC**: Power Amplifier Digital-to-Analog Converter and Analog-to-Digital Converter.
- Int./Dec.**: Interpolator/Decoder, connected to the OFDM PHY and I/Q-DAC I/Q-ADC.
- I/Q-DAC I/Q-ADC**: In-Phase/Quadrature Digital-to-Analog Converter and Analog-to-Digital Converter.
- AGC**: Automatic Gain Control, connected to the OFDM PHY, Int./Dec., and RF-Control.
- RSSI-ADC**: Received Signal Strength Indicator Analog-to-Digital Converter, connected to the AGC.
- MMI_CCK**: Master Module Interface Clocked Carrier/Karlovitz/Chirp Waveform signal, connected to the CCK PHY.
- CLK22**: 22 MHz clock signal, connected to the Resampling block.
- MMI-APB**: Master Module Interface Advanced Peripheral Bus, connected to the APB-Master.
- APB-Master**: Advanced Peripheral Bus Master, connected to the MMI-APB.

The diagram shows the interconnections between these components, including data paths, control signals, and clock signals.